

IN THE SPECIFICATION

Please amend the paragraph beginning at page 8, line 14 of the specification as follows:

A photoresist layer 500 is coated on the upper conductive layer 400. The photo resistive layer 500 is then exposed by a light L1 that passes through the second photo mask, which is shown in Figs. 3B and 3D. As a result, the photoresist layer 500 is defined to have a first pattern region P1, a second pattern region P2, and a third pattern region P3 corresponding to the first to third upper opaque patterns 400a, 400b, and 400c of Fig. 3B and an exposure region E between the first to third pattern regions P1, P2 and P3. The applied light L1 is reflected on the sloped surfaces of the upper conductive layer 400. As a result, a reflected light L2 can be directed into regions of the photoresist layer 500 between the pattern regions P1, P2, and P3.